

NCE Automotive N-Channel Super Trench Power MOSFET

Description

The NCEAP60T15G uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

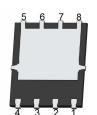
- Automotive application
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- •V_{DS} =60V,I_D =196A (Silicon Limited) $R_{DS(ON)} < 3.1 m\Omega$ @ V_{GS}=10V (Typ:2.8m Ω)
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175°C operating temperature
- Pb-free lead plating;RoHS compliant
- Halogen-free according to IEC61249-2-21
- 100% UIS tested
- 100% ΔVds tested
- AEC-Q101 qualified

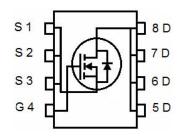
DFN 5X6-8L





Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AP60T15G	NCEAP60T15G	DFN5X6-8L	Ø330mm	12mm	5000units

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous (Silicon Limited)	I _D	196	A
Drain Current-Continuous(T _C =100 ℃)	I _D (100℃)	139	А
Drain Current-Continuous (Package Limited)	I _D	120	А
Pulsed Drain Current	I _{DM}	480	А
Maximum Power Dissipation	P _D	240	W
Derating factor		1.6	W/°C
Single pulse avalanche energy (Note 1)	E _{AS}	973	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	0.625	°C/W
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NCEAP60T15G

Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						l
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.0	2.8	4.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	2.8	3.1	mΩ
Forward Transconductance	G FS	V _{DS} =10V,I _D =20A	-	50	-	S
Dynamic Characteristics						
Input Capacitance	C _{lss}	V 20V/V 0V	-	4500	-	pF
Output Capacitance	Coss	V _{DS} =30V,V _{GS} =0V, F=1.0MHz		965	-	pF
Reverse Transfer Capacitance	C _{rss}			24	-	pF
Switching Characteristics (Note 2)						
Turn-on Delay Time	t _{d(on)}		-	10	-	nS
Turn-on Rise Time	t _r	V_{DD} =30 V , I_D =20 A	-	22	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =4.7 Ω	-	35	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	V _{DS} =30V,I _D =20A,	-	70	-	nC
Gate-Source Charge	Q _{gs}		-	19	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		15.3	-	nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current	Is		-	-	120	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 100A	-	56	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs	-	80	-	nC

Notes:

^{1.} EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=30V,VG=10V,L=0.5mH,Rg=25 Ω

^{2.} Guaranteed by design, not subject to production

^{3.} These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of TJ(MAX)=175°C. The SOA curve provides a single pulse rating.



Typical Electrical and Thermal Characteristics

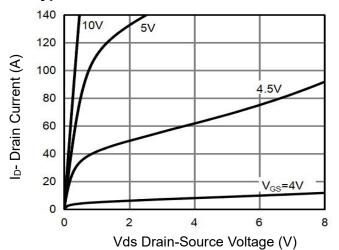


Figure 1 Output Characteristics

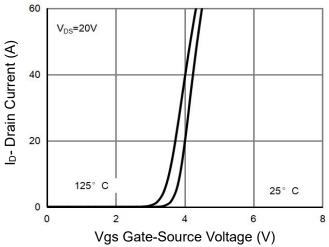


Figure 2 Transfer Characteristics

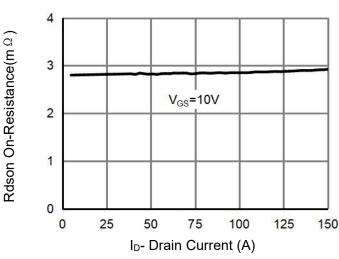


Figure 3 Rdson- Drain Current

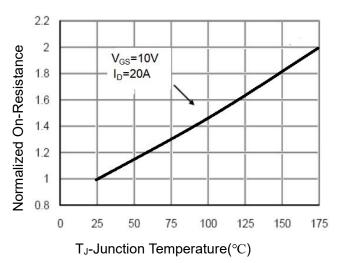


Figure 4 Rdson-Junction Temperature

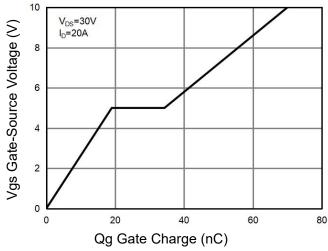


Figure 5 Gate Charge

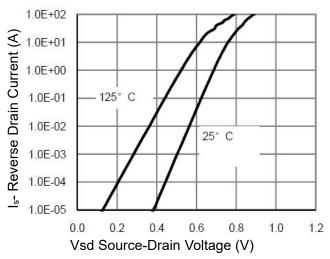


Figure 6 Source- Drain Diode Forward



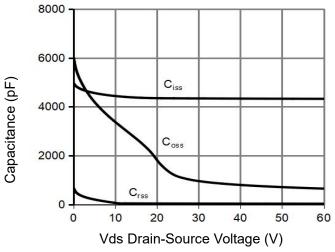


Figure 7 Capacitance vs Vds

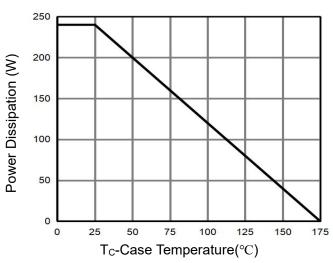


Figure 9 Power De-rating

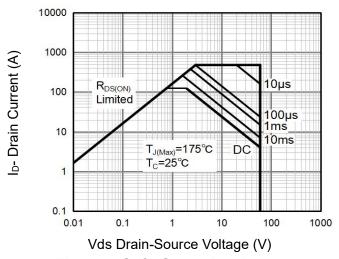


Figure 8 Safe Operation Area (Note3)

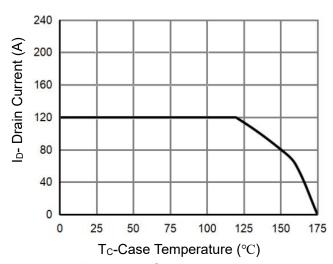


Figure 10 Current De-rating

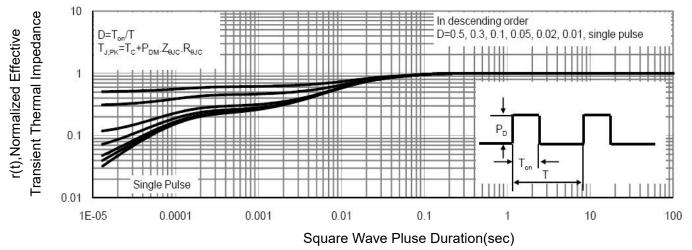
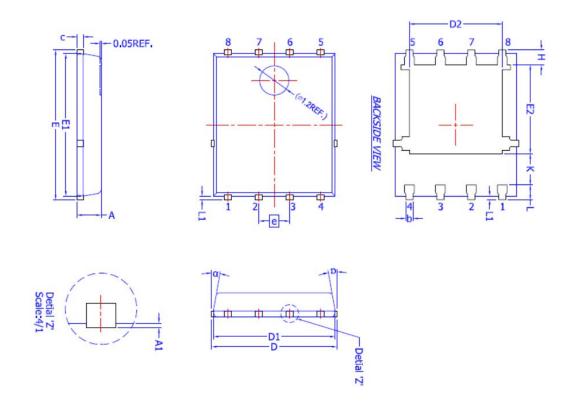


Figure 11 Normalized Maximum Transient Thermal Impedance



PDFN5X6-8L Package Information



DIM.	MIL	LIMETE	RS
	MIN.	NOM.	МАХ.
Α	0.90	1.00	1.10
A1	0	-	0.05
Ь	0.30	0.40	0.50
С	0.20	0.25	0.30
D	5.15 BSC		
D1		5.00 BSC	7
D2	3.76	3.81	3.86
E		6.15 BSC	:
E1	5.80	5.85	5.90
E2	3.45	3.65	3.85
е	1.27 BSC		
Н	0.51	0.61	0.71
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.08	0.15	0.23
α	10°	110	12°



http://www.ncepower.com

NCEAP60T15G

Revision History

Revision	Date	Subjects
V1.0	2023.07.05	Product data sheet

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